

N-Channel 40-V (D-S) MOSFET

PRODUCT SUMMARY						
V _{DS} (V)	$R_{DS(on)}(\Omega)$	I _D (A) ^{a, c}	Q _g (Typ.)			
40	0.0050 at V _{GS} = 10 V	85	120 nC			
	0.0065 at V _{GS} = 4.5 V	70	120110			

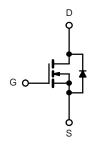
FEATURES

- TrenchFET® Power MOSFET
- 100 % R_g and UIS Tested



APPLICATIONS

- Synchronous Rectification
- Power Supplies



N-Channel MOSFET

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Parameter	Symbol	Limit	Unit		
Drain-Source Voltage		V _{DS}	40	.,,	
Gate-Source Voltage		V _{GS}	± 25	V	
	T _C = 25 °C		85 ^{a, c}		
Continuous Proin Current (T. – 175 °C)	T _C = 70 °C		70 ^c		
Continuous Drain Current (T _J = 175 °C)	T _A = 25 °C	I _D	59 ^b		
	T _A = 70 °C		53 ^b	_ ^	
Pulsed Drain Current		I _{DM}	250		
Avalanche Current Pulse	L = 0.1 mH		80		
Single Pulse Avalanche Energy	L=0.1 IIII	E _{AS}	320	V	
Continuous Source-Drain Diode Current	T _C = 25 °C	I.	110 ^{a, c}	Λ	
Continuous Source-Drain Diode Current	T _A = 25 °C	I _S	2.6 ^b	Α	
	T _C = 25 °C		312 ^a		
Mariana Barra Birain atau	T _C = 70 °C	Б	200	W	
Maximum Power Dissipation	T _A = 25 °C	P _D	3.13 ^b		
	T _A = 70 °C		2.0 ^b		
Operating Junction and Storage Temperature R	T _J , T _{stq}	- 55 to 150	°C		

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Typical	Maximum	Unit			
Maximum Junction-to-Ambient ^b	Steady State	R _{thJA}	32	40	°C/W		
Maximum Junction-to-Case	Steady State	R_{thJC}	0.33	0.4	C/VV		

Notes:

- a. Based on $T_C = 25$ °C.
- b. Surface Mounted on 1" x 1" FR4 board.
- c. Calculated based on maximum junction temperature. Package limitation current is $110 \ A$.



Parameter	Symbol	Test Conditions	Min.	Тур.	Max.	Unit	
Static							
Drain-Source Breakdown Voltage	V _{DS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$	40			V	
V _{DS} Temperature Coefficient	$\Delta V_{DS}/T_{J}$	I _D = 250 μA		41		mV/°C	
V _{GS(th)} Temperature Coefficient	$\Delta V_{GS(th)}/T_{J}$	10 – 200 μπ		- 8		mv/·C	
Gate-Source Threshold Voltage	V _{GS(th)}	$V_{DS} = V_{GS}$, $I_D = 250 \mu A$	1.2		2.5	V	
Gate-Source Leakage	I _{GSS}	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$			± 100	nA	
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 40 V, V _{GS} = 0 V			1	μA	
Zero Gate Voltage Drain Gurrent	פפטי	$V_{DS} = 40 \text{ V}, V_{GS} = 0 \text{ V}, T_{J} = 55 ^{\circ}\text{C}$			10	μΛ	
On-State Drain Current ^a	I _{D(on)}	$V_{DS} \ge 5 \text{ V}, V_{GS} = 10 \text{ V}$	120			Α	
Drain Course On State Resistance	Rno()	$V_{GS} = 10 \text{ V}, I_D = 30 \text{ A}$		0.0050	0.0064	Ω	
Drain-Source On-State Resistance ^a	R _{DS(on)}	$V_{GS} = 4.5 \text{ V}, I_D = 20 \text{ A}$		0.0065	0.0075	52	
Forward Transconductance ^a	9 _{fs}	$V_{DS} = 15 \text{ V}, I_{D} = 30 \text{ A}$		180		S	
Dynamic ^b							
Input Capacitance	C _{iss}			2380		pF	
Output Capacitance	C _{oss}	$V_{DS} = 20 \text{ V}, V_{GS} = 0 \text{ V}, f = 1 \text{ MHz}$		550			
Reverse Transfer Capacitance	C _{rss}			250			
Total Gate Charge	Q_g			120	180	nC	
Gate-Source Charge	Q _{gs}	$V_{DS} = 20 \text{ V}, V_{GS} = 10 \text{ V}, I_{D} = 20 \text{ A}$		40			
Gate-Drain Charge	Q _{gd}			22			
Gate Resistance	R _g	f = 1 MHz		0.85	1.3	Ω	
Turn-On Delay Time	t _{d(on)}			20	30		
Rise Time	t _r	$V_{DD} = 20 \text{ V}, R_{L} = 1.0 \Omega$		11	17	1	
Turn-Off Delay Time	t _{d(off)}	$I_D\cong 20$ A, $V_{GEN}=10$ V, $R_g=1$ Ω		77	115		
Fall Time	t _f			10	15		
Turn-On Delay Time	t _{d(on)}			102	155	ns	
Rise Time	t _r	V_{DD} = 20 V, R_L = 1.0 Ω		62	95		
Turn-Off Delay Time	t _{d(off)}	$I_D\cong$ 20 A, V_{GEN} = 4.5 V, R_g = 1 Ω		180	270		
Fall Time	t _f			60	90		
Drain-Source Body Diode Characteristic	s						
Continuous Source-Drain Diode Current	I _S	$T_C = 25 ^{\circ}C$			110	А	
Pulse Diode Forward Current ^a	I _{SM}				200		
Body Diode Voltage	V _{SD}	I _S = 20 A		0.8	1.2	V	
Body Diode Reverse Recovery Time	t _{rr}			50	75	ns	
Body Diode Reverse Recovery Charge	Q _{rr}	I _F = 20 A, di/dt = 100 A/µs, T _{.I} = 25 °C		70	105	nC	
Reverse Recovery Fall Time	t _a	$\frac{1}{1}$ $\frac{1}$		30	_		
Reverse Recovery Rise Time	t _b			20		ns	

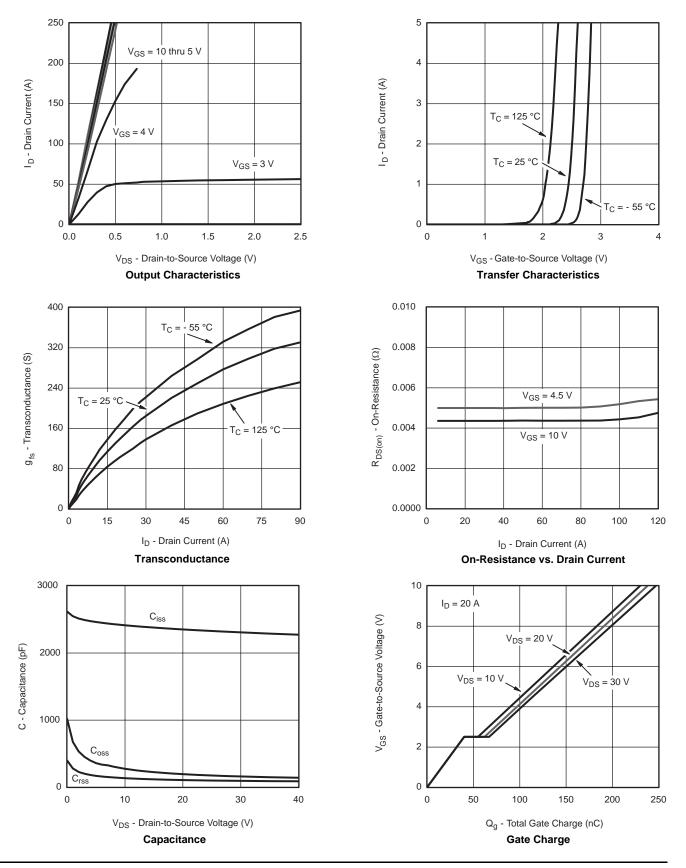
Notes:

- a. Pulse test; pulse width $\leq 300~\mu s,$ duty cycle $\leq 2~\%.$
- b. Guaranteed by design, not subject to production testing.

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

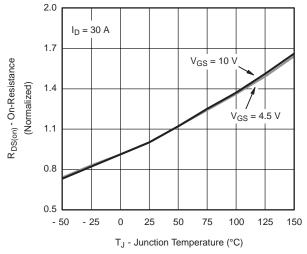


TYPICAL CHARACTERISTICS 25 °C, unless otherwise noted

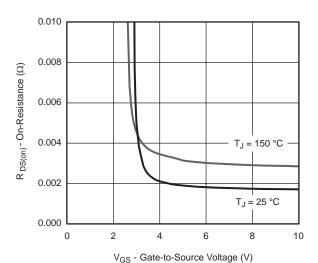




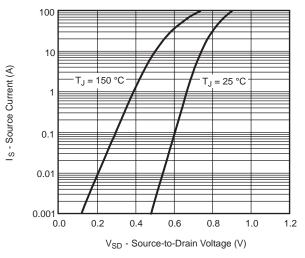
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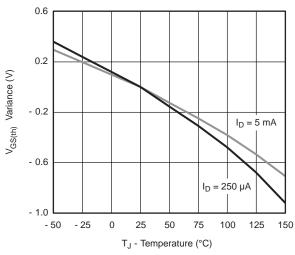
On-Resistance vs. Junction Temperature



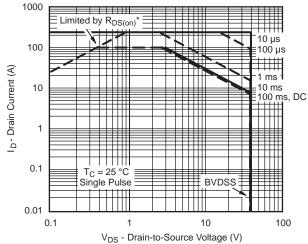
On-Resistance vs. Gate-to-Source Voltage



Forward Diode Voltage vs. Temperature



Threshold Voltage

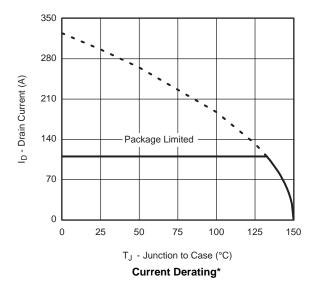


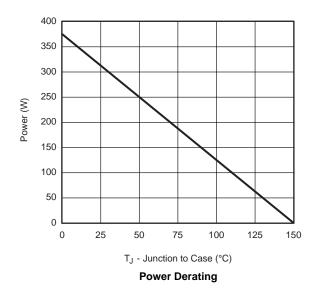
* V_{GS} > minimum V_{GS} at which $R_{DS(on)}$ is specified

Safe Operating Area, Junction-to-Ambient

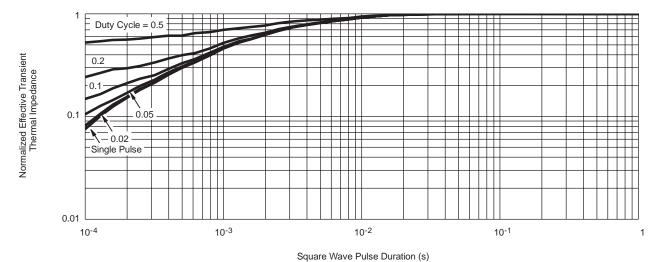


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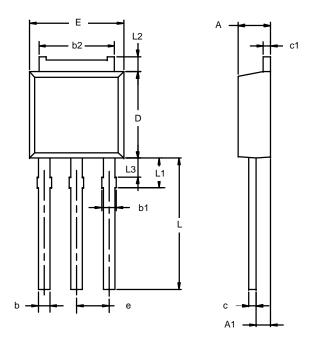
^{*} The power dissipation P_D is based on $T_{J(max)} = 150$ °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



Normalized Thermal Transient Impedance, Junction-to-Case



TO-251AA (DPAK)



Note:	Dimension	L3 is for	reference	only.
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	MILLIM	IETERS	INC	HES	
Dim	Min	Max	Min	Max	
Α	2.21	2.38	0.087	0.094	
A1	0.89	1.14	0.035	0.045	
b	0.71	0.89	0.028	0.035	
b1	0.76	1.14	0.030	0.045	
b2	5.23	5.43	0.206	0.214	
С	0.46	0.58	0.018	0.023	
с1	0.46	0.58	0.018	0.023	
D	5.97	6.22	0.235	0.245	
E	6.48	6.73	0.255	0.265	
е	2.28	BSC	0.090	BSC	
L	3.89	9.53	0.153	0.375	
L1	1.91	2.28	0.075	0.090	
L2	0.89	1.27	0.035	0.050	
L3	1.15	1.52	0.045	0.060	
ECN: S-03946—Rev. E, 09-Jul-01 DWG: 5346					

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